

A Product Line of Diodes Incorporated



SPECIFICATION FOR APPROVAL

CUSTOMER				
NOMINAL FREQUENCY	50.000000 MHz			
PRODUCT TYPE	TYPE FW 2.0x1.6 SEAM SEALED CRYSTAL			
SPEC. NO. (P/N)	FW500008Q			
CUSTOMER P/N				
ISSUE DATE	June 21, 2018			
VERSION	Α			

APPROVED	PREPARED	QA
Brenda	Nikhi Lu	Dong Jang

Diodes Incorporated

No.2, Ziqiang 5th Rd., Zhongli Industrial Park, Zhongli Dist., Taoyuan City 32063, Taiwan (R.O.C.)

TEL: 886-3-451-8888 FAX: 886-3-461-3865 https://www.diodes.com

- *Pb-free
- *RoHS Compliant
- *HF-Halogen Free
- *REACH Compliant
- *AEC-Q200 Compliant

E0-R-4-014 Rev. F

FW5000008Q

VER. A 21-Jun-18

VERSION HISTORY

Version No.	Version Date	Description	Notes
Α	Jun.21,2018	Initial Release	

FW5000008Q

VER. A 21-Jun-18

ELECTRICAL SPECIFICATIONS

Item	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	50.000000	MHz	
Mode of Oscillation	МО	AT Cut-Fundamental		
Calibration Load Capacitance	CL	10	pF	
Calibration Tolerance	FL	±10	ppm	at 25°C±3°C
Operating Temperature Range	TR	-40 to +85	°C	
Frequency Stability (Frequency Deviation over the Operating Temperature Range)	F/T	±15	ppm	Reference to the Frequency at 25°C
Operating Drive Level		10	μW	
Maximum Drive Level		100	μW	Max.
Equivalent Series Resistance	ESR	60	Ω	Max
Shunt Capacitance	C0	3	pF	Max
Aging at 25°C		±3	ppm	Max, 1st year
Storage Temperature		-55 to +125	°C	
Insulation Resistance		500	МΩ	Min

※ This product doesn't include harmful substance that stipulated by SONY SS-00259 Level 1 and S-AT2-001 Level 1 standard. RoHS Compliant (Pb - Free).



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AEC-Q200 RELIABILITY TEST SPECIFICATIONS:

1. Initial

1.1 Physical Dimensions: JESD22, Method JB1-100

1.2 External Visual: MIL-STD-883, Method 2009

1.3 Freq. Vs. Temperature: Per Specification/Datasheet

2. Mechanical

2.1 Mechanical Shock: MIL-STD-202 Method 213

2.2 Vibration: MIL-STD-202 Method 204

2.3 Solderability: J-STD-002

2.4 Board Flex: AEC Q200-005

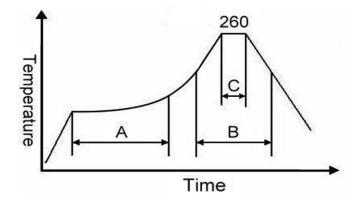
2.5 Terminal Strength (SMD): AEC Q200-006

3.Environmental

- 3.1 Temp Cycle: JESD22, Method JA-104
- 3.2 Resistance to Solder Heat: MIL-STD-202 Method 210
- 3.3 High Temperature Operating Life: MIL-STD-202, Method 108
- 3.4 High Temp Exposure: MIL-STD-202, Method 108
- 3.5 High Temp & High Humidity: MIL-STD-202, Method 103
- 3.6 Thermal Shock: MIL-STD-202, Method 107

SUGGESTED IR REFLOW PROFILE

*As per IPC-JEDEC J-STD-020D



N	ote	
IV	OLE	

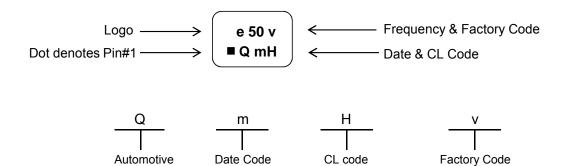
	Stage	Temperature	Time
Α	Preheat	150~200°C	60~120 Sec
В	Primary Heat	217°C	60~150 Sec
С	Peak	260°C	10 Sec



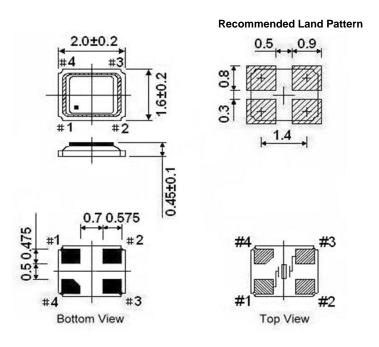
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MARKING



MECHANICAL DRAWINGS (Scale: None. Dimensions are in mm.)



** Recommended - Pin 1 & 3: CRYSTAL Pin 2 & 4: GND

Notes:

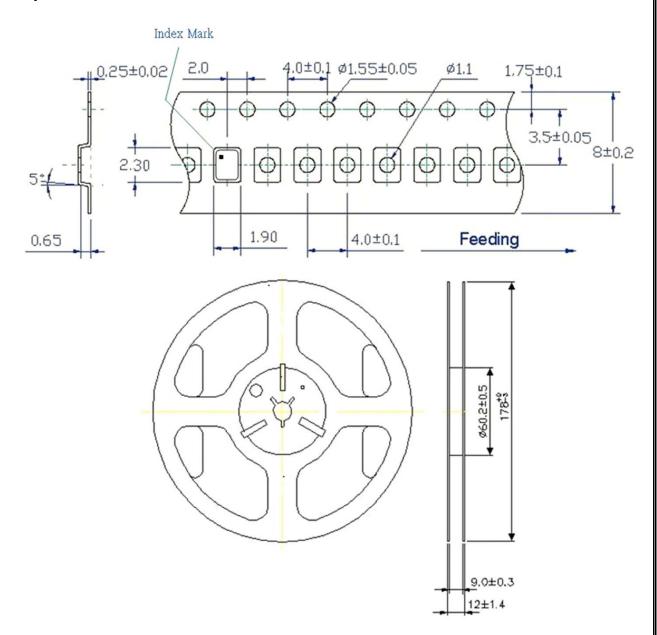
- Package drawings are for reference only, and the appearances of objects may vary.
 Actual packages are based on the real product.
- 2. The marking dot denotes Pin#1.
- 3. The position and shape of the chamfer pin may vary and are based on the real product.



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Tape & Reel



- 1. 230mm minimum leafer which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.
- 2. 160mm minimum trailer of empty carrier tape sealed with cover tape.

TYPE FW 2.0x1.6 SEAM SEALED CRYSTAL FW5000008Q VER. A 21-Jun-18 **PACKING** Start Begin **End** 3000pcs-Product Tape Inner Packing Carton Storeroom Label Blue Qualified Label Storeroom Storeroom Label Deliver Packing Carton (L29*W24*H30) Green Qualified Label

